



PK469 (v1.0) Jul 29, 2011

100% Material Declaration Data Sheet FGG900 Spartan-6

Average Weight: 3.949 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.090946	2.303
	Silicon	7440-21-3	100.00	Main material	0.090946	
Die Attach Material					0.016016	0.406
	Silver	7440-22-4	77.50	Main material	0.012412	
	Bismaleimide monomer	Trade Secret	15.00	Main material	0.002402	
	Acrylate monomer	Trade Secret	7.50	Main material	0.001201	
Mold Compound					1.876994	47.531
	Solid Epoxy Resin	Trade Secret	5.00	Main material	0.093850	
	Phenol Resin	Trade Secret	5.00	Main material	0.093850	
	Fused Silica	60676-86-0	87.45	Main material	1.641431	
	Metal Hydroxide	Trade Secret	2.00	Main material	0.037540	
	Carbon Black	1333-86-4	0.55	Main material	0.010323	
Gold Wire					0.023056	0.584
	Gold	7440-57-5	99.05	Main material	0.022837	
	Palladium	7440-05-3	0.95	Main material	0.000219	
Solder Balls					0.751829	19.038
	Tin	7440-31-5	96.50	Main material	0.725515	
	Silver	7440-22-4	3.00	Main material	0.022555	
	Copper	7440-50-8	0.50	Main material	0.003759	
Substrate					1.190159	30.138
	Copper	7440-50-8	28.19	Main material	0.335483	
	Nickel	7440-02-0	4.13	Main material	0.049192	
	Gold	7440-57-5	0.30	Main material	0.003529	
	BT (core)	21645-51-2 7440-50-8 Epoxy resin	59.49	Main material	0.708012	
	Solder mask	14807-96-6 7727-43-7 7631-86-9 34590-94-8 85954-11-6	7.89	Main material	0.093943	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
07/29/11	1.0	Initial Xilinx release.

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